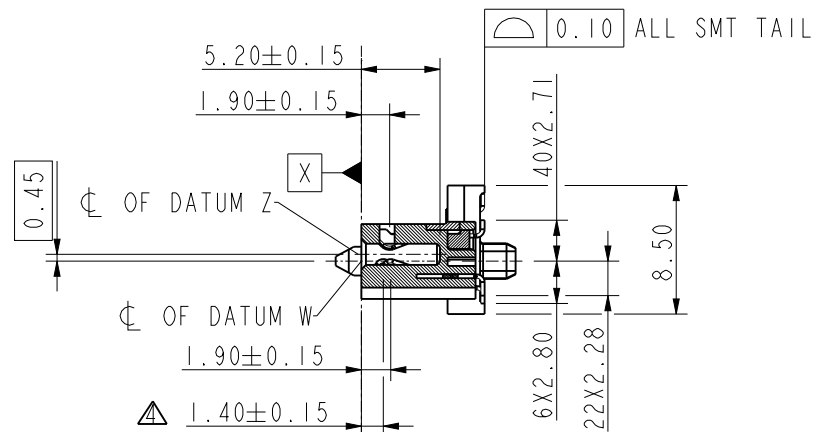
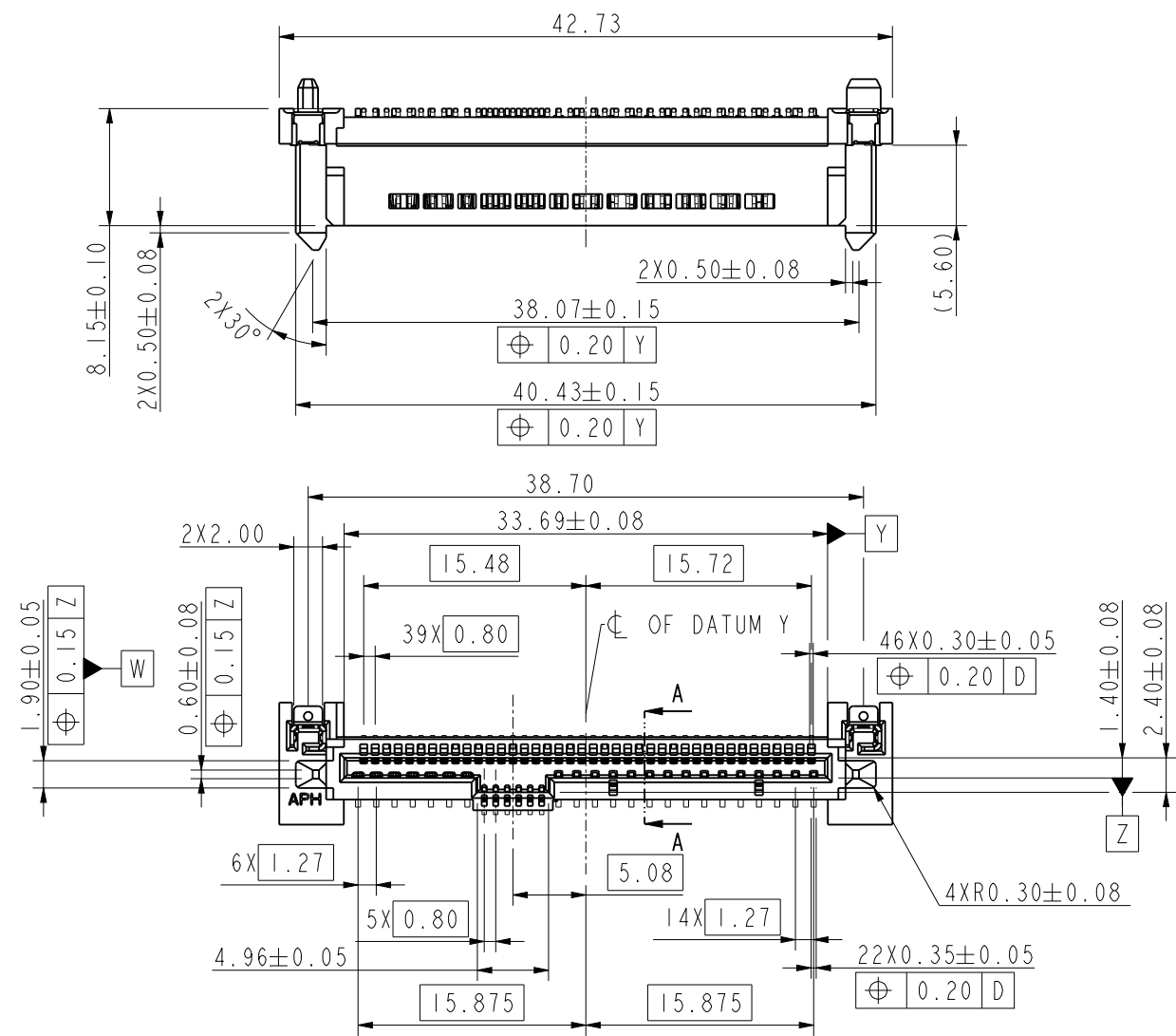


revision history				
rev	ecn no	description	dr	date
1	ELX-CD-FXXXX-I	FIRST RELEASE	Teng	2021/09/15
2	ELX-CD-FXXXX-I	40P PCB PAD 1.60 WAS 1.80	Teng	2022/09/22
3	ELX-CD-F3086-I	ADD PACKING SPEC	Teng	2022/09/29

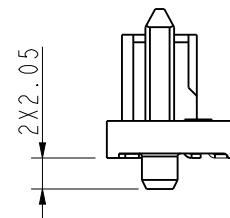
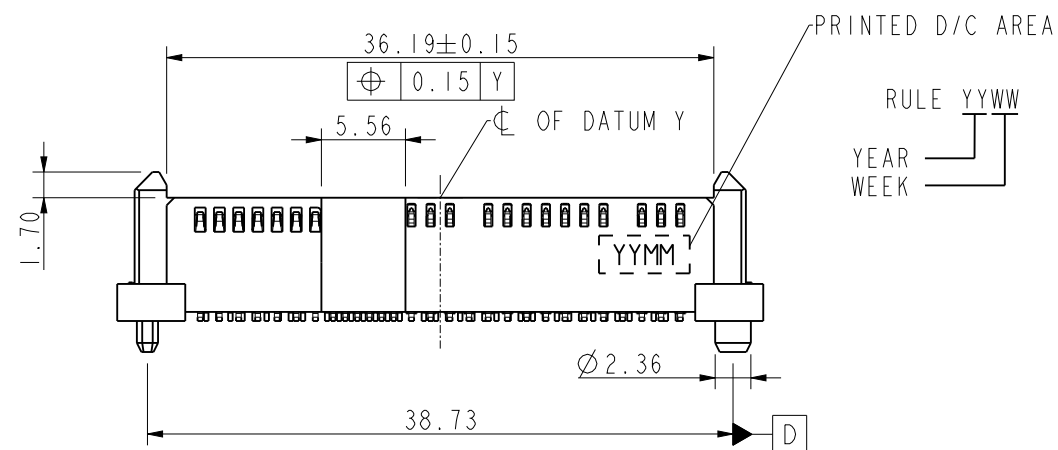


SECTION A-A

- NOTE:
- MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94-V0, HALOGEN FREE.
 - CONTACT: PHOSPHOR BRONZE
 - BOARD LOCK: COPPER ALLOY
 - PLATING:
 - CONTACTS: MATING AREA PLEASE REFER TO PN SYSTEM, 1.27um MIN Ni UNDERPLATED SOLDER TAIL 2.54um MIN MATTE TIN, 1.27um MIN Ni UNDERPLATED
 - BOARD LOCK: 2.54um MIN MATTE TIN 2.54um MIN Ni UNDERPLATED
 - ELECTRICAL PERFORMANCE:
 - CURRENT RATING: 1.5A/PER PIN (POWER SECTION).
 - CONTACT RESISTANCE: 30mΩ MAX (INITIAL)
 - INSULATION RESISTANCE: 1000MΩ MIN
 - DIELECTRIC STRENGTH: 500 VAC FOR 1 MINUTE
 - OPERATION TEMPERATURE: -40°C~+85°C
 - PREMATING AT P4 & P12.
 - SUPPORT PCIe GEN5.
 - ALL GND PINS CONNECT TOGETHER.
S1, S4, S7, E9, E12, E15, S8, S11, S14, S16, S19, S22, S25, S28, E19, E22
 - MATERIAL SHOULD BE FULFILLED AMPHENOL SPEC#S-SN-002 AND SPEC#S-SN-004
 - ORDER P/N SYSTEM: PSAS5F313015XXX

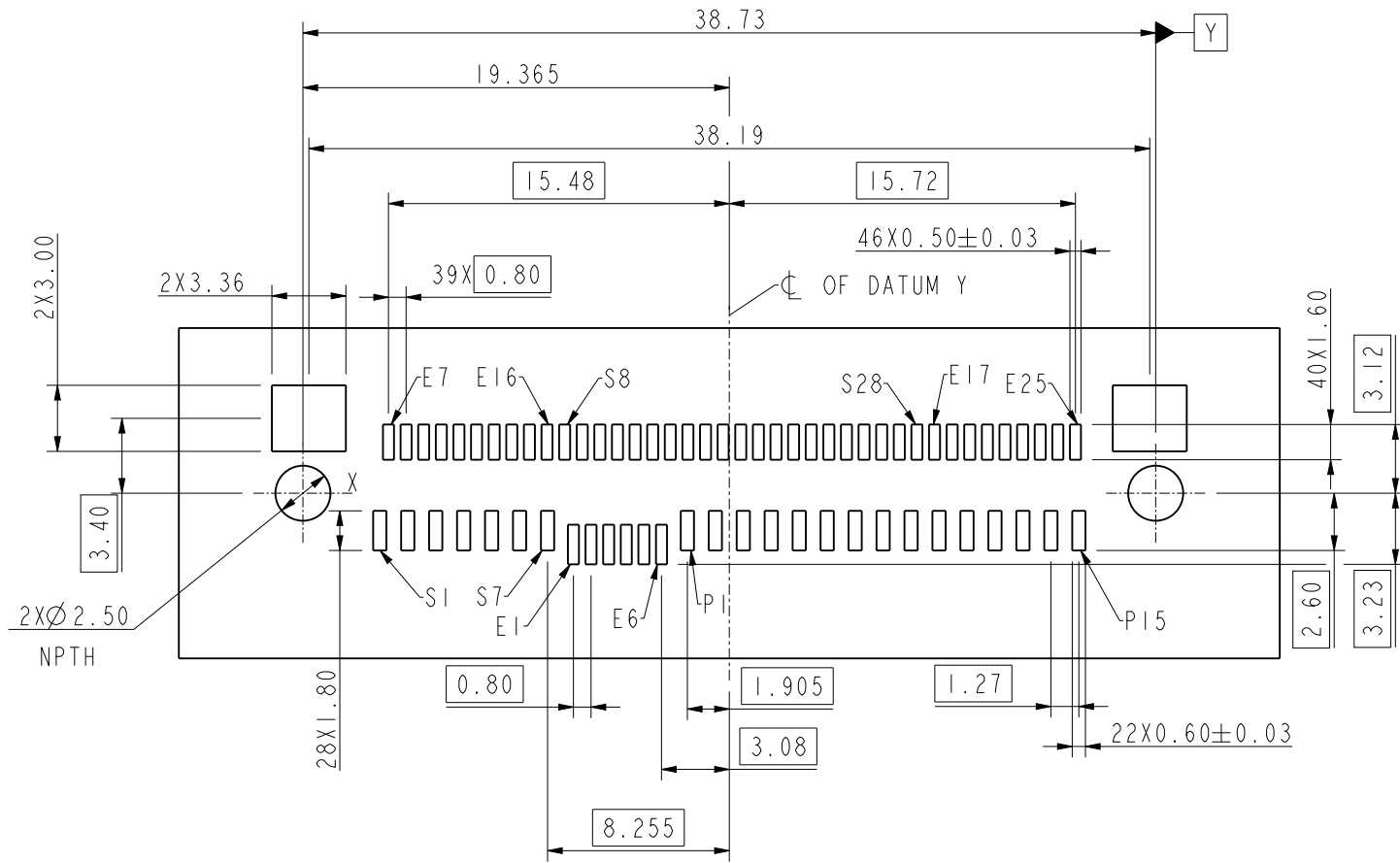
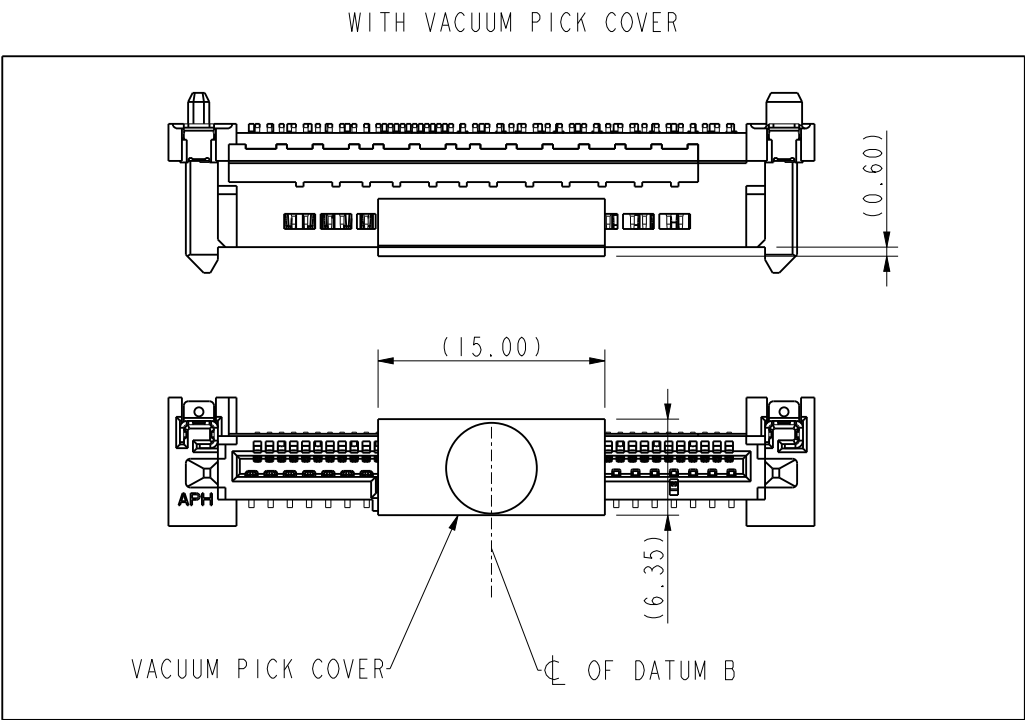
MATING AREA PLATING
1- 0.76um MIN Au.
2- 0.38um MIN Au.
3- GOLD FLASH

PACKING SYSTEM
NIL- TRAY WITHOUT PICK-UP CAP
C- TRAY WITH PICK-UP CAP
TR- TAPE AND REEL WITH PICK-UP CAP
NT- TAPE AND REEL WITH OUT PICK-UP CAP



spec ref				dr		Teng.Cao		Oct.08,2022		Amphenol				mm		scale		size					
tolerance std				TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Teng.Cao						Oct.08,2022		ecn no				ELX-CD-F3086-1		A3	
						rvwr																	
						appr										amphenol-icc.com				rel level			
surface		linear		0.X		±0.50		projection		title		PCIe/SAS VERTICAL SMT				dwg no		PSAS5F313015XXX				rev	
				0.XX		±0.25																	
				0.XXX		±0.20																	
				angular		0°																	
						</																	

revision history				
rev	ecn no	description	dr	date
-	-	REFER TO SHEET 1	-	-



RECOMMENDED PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCE ±0.05(PCB THICKNESS:1.00~2.00MM)

spec ref				dr		Teng.Cao		Oct.08,2022		Amphenol				mm		scale		size						
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Teng.Cao		Ocp.08,2022						amphenol-icc.com				ecn no		ELX-CD-F3086-1		A3		
				rvwr														rel level				RELEASE		
				appr																				
surface		✓		projection				title		PCIe/SAS VERTICAL SMT				drag no	PSAS5F3I30I5XXX				rev					
																					cat. no.			
															product family		PSAS						sheet 2 of 3	
															angular		0°		±3°					

A

C

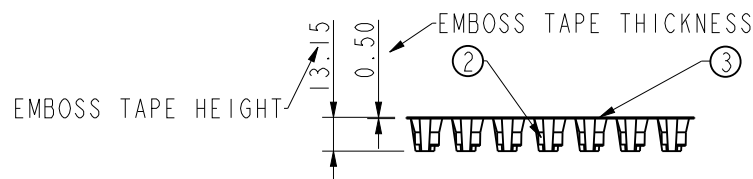
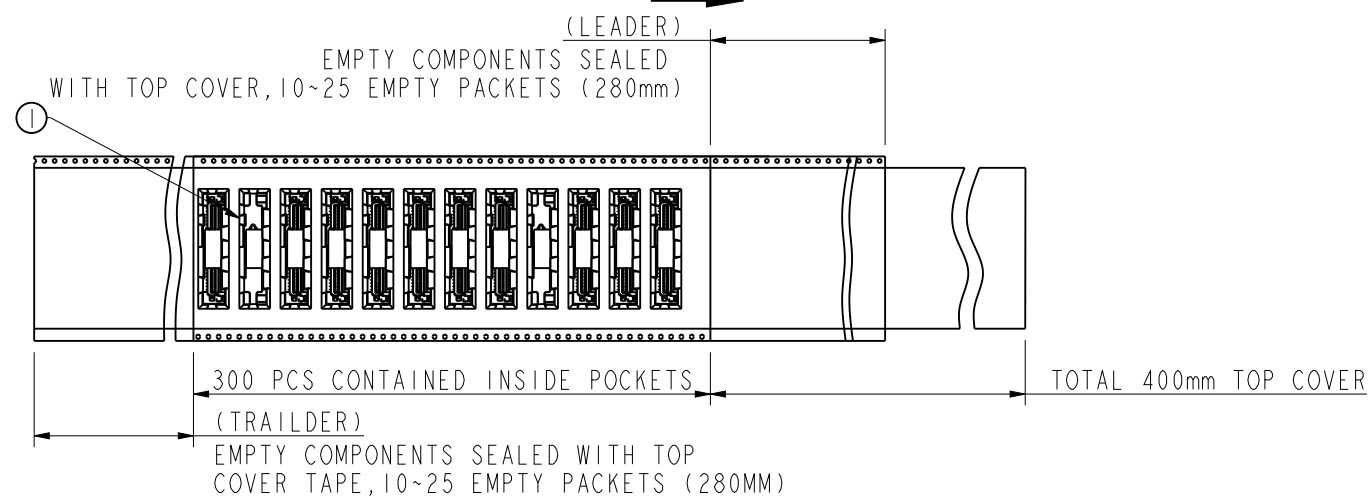
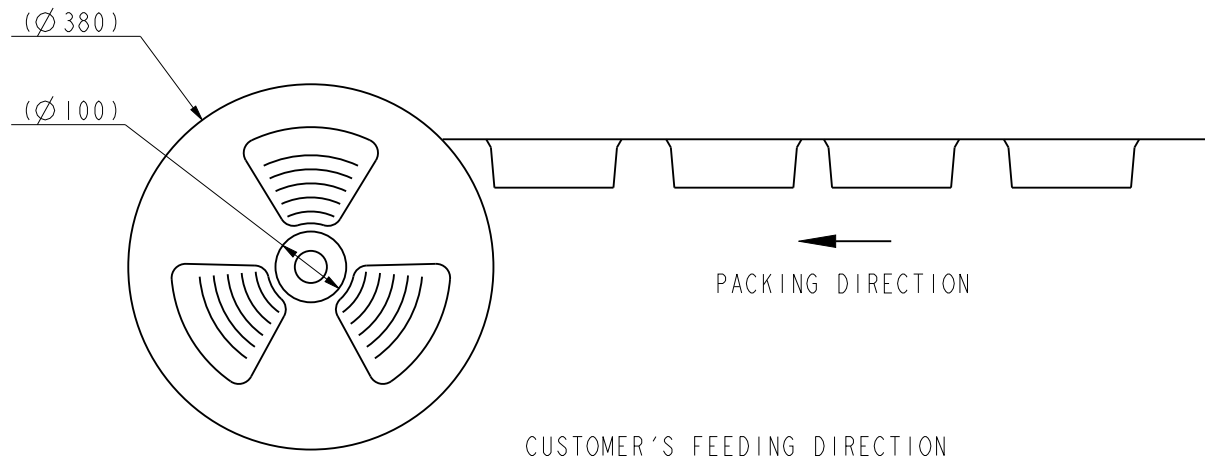
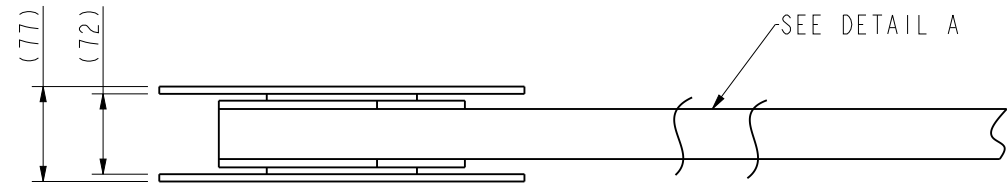
D

A

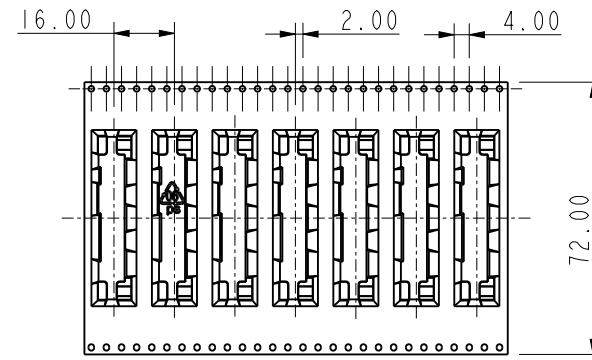
B

C

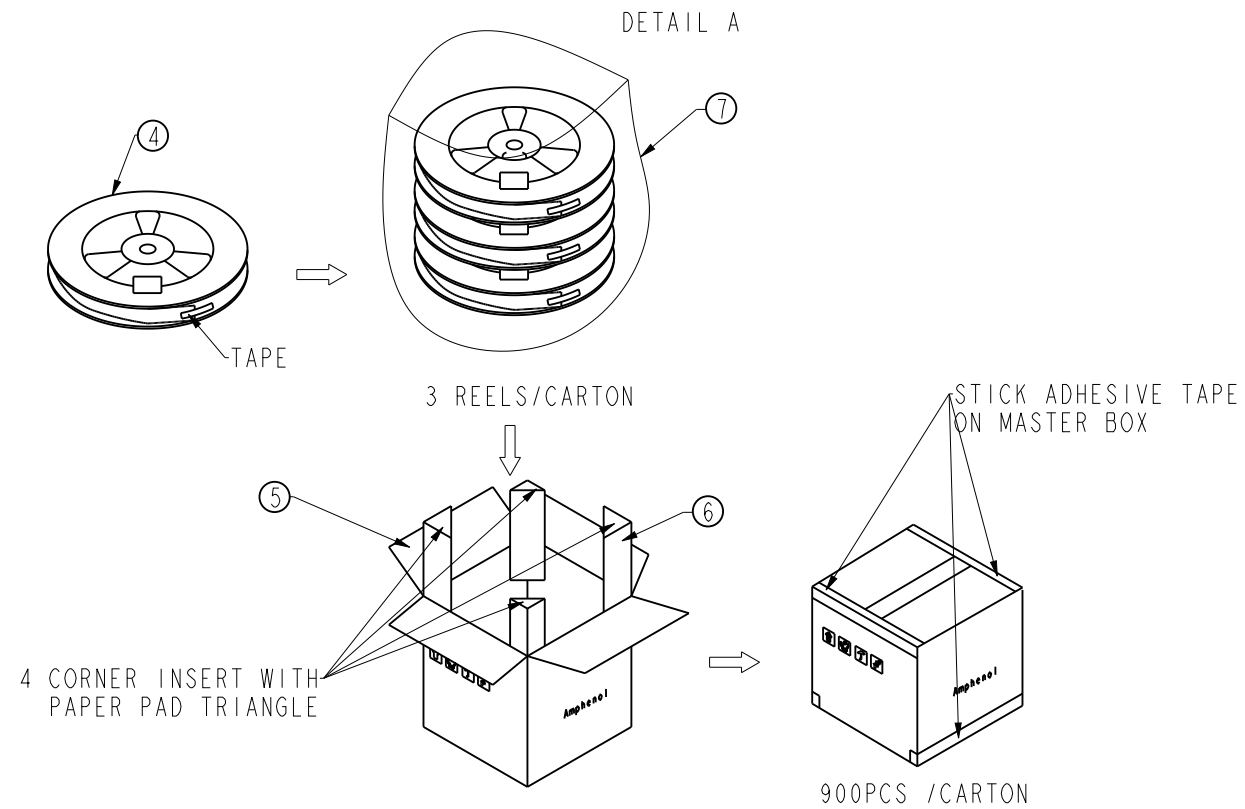
D



revision history				
rev	ecn no	description		date



SCALE 1:2



7	PLASTIC BAG	NA
6	PAPER PAD TRIANGLE	CORRUGATED FIBERBOARD
5	MASTER BOX	CORRUGATED FIBERBOARD
4	PP REEL	PP
3	TOP COVER TAPE	PET
2	EMBOSS TAPE	POLYSTYRENE
1	CONNECTOR	NA
ITEM	DESCRIPTION	MATERIAL

spec ref				dr	Teng.Cao	Oct.08,2022	Amphenol		scale	size
tolerance std				eng	Teng.Cao	Oct.08,2022			2:1	A3
				rvwr					ecn no	ELX-CD-F3086-1
				appr					rel level	RELEASE
surface				projection				amphenol-icc.com		
				PCIE/SAS VERTICAL SMT				900PCS /CARTON		
								PSAS5F3I30I5XXX		rev
								cat. no.		3
								PSAS		sheet 3 of 3